General Purpose Transistor NPN Silicon

Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

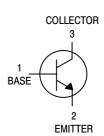


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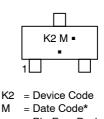
http://onsemi.com



SOT-23 (TO-236) CASE 318-08 STYLE 6



MARKING DIAGRAM



= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BCW72LT1G	SOT–23 (Pb–Free)	3,000 / Tape & Reel
SBCW72LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Collector – Emitter Voltage	V _{CEO}	45	Vdc	
Collector – Base Voltage	V _{CBO}	50	Vdc	
Emitter-Base Voltage	V _{EBO}	5.0	Vdc	
Collector Current – Continuous	۱ _C	100	mAdc	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	PD	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

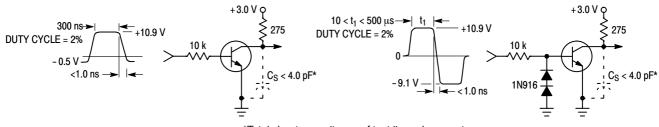
1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, V_{EB} = 0)$	V _{(BR)CEO}	45	_	_	Vdc
Collector – Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, V_{EB} = 0)$	V _{(BR)CES}	45	-	_	Vdc
Collector – Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	50	_	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	5.0	_	_	Vdc
Collector Cutoff Current $(V_{CB} = 20 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 20 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	I _{CBO}			100 10	nAdc μAdc
ON CHARACTERISTICS					
DC Current Gain (I _C = 2.0 mAdc, V _{CE} = 5.0 Vdc)	h _{FE}	200	_	450	_
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}, I_B = 0.5 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}, I_B = 2.5 \text{ mAdc}$)	V _{CE(sat)}		_ 0.21	0.25 -	Vdc
Base – Emitter Saturation Voltage $(I_C = 50 \text{ mAdc}, I_B = 2.5 \text{ mAdc})$	V _{BE(sat)}	_	0.85	_	Vdc
Base – Emitter On Voltage (I _C = 2.0 mAdc, V _{CE} = 5.0 Vdc)	V _{BE(on)}	0.6	_	0.75	Vdc
SMALL-SIGNAL CHARACTERISTICS	•				
Current – Gain – Bandwidth Product (I _C = 10 mAdc, V _{CE} = 5.0 Vdc, f = 100 MHz)	f _T	-	300	_	MHz
Output Capacitance (I _E = 0, V _{CB} = 10 Vdc, f = 1.0 MHz)	C _{obo}	_	_	4.0	pF
Input Capacitance ($I_E = 0$, $V_{CB} = 10$ Vdc, f = 1.0 MHz)	C _{ibo}	_	9.0	_	pF
Noise Figure (I _C = 0.2 mAdc, V _{CE} = 5.0 Vdc, R _S = 2.0 kΩ, f = 1.0 kHz, BW = 200 Hz)	NF	-	-	10	dB

EQUIVALENT SWITCHING TIME TEST CIRCUITS



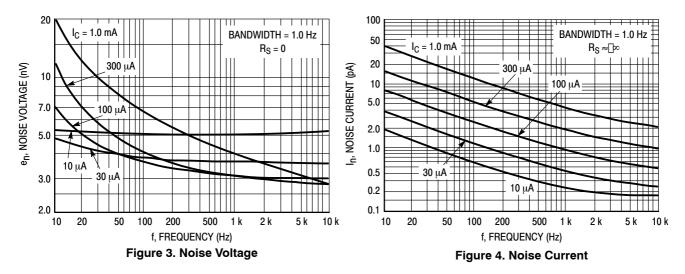
*Total shunt capacitance of test jig and connectors

Figure 1. Turn-On Time

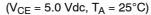
Figure 2. Turn-Off Time

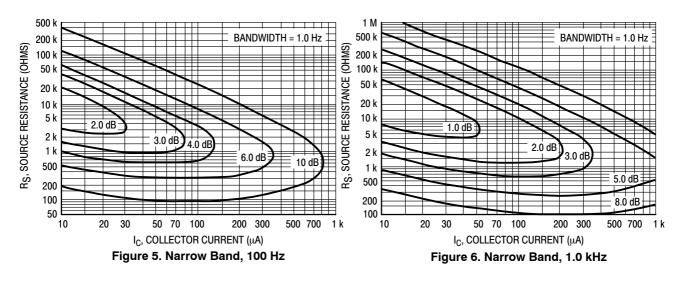
TYPICAL NOISE CHARACTERISTICS

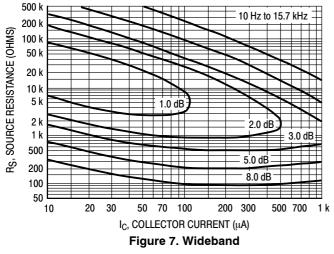
 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$



NOISE FIGURE CONTOURS







Noise Figure is defined as:

$$NF = 20 \log_{10} \left(\frac{e_{n}^{2} + 4KTR_{S} + I_{n}^{2}R_{S}^{2}}{4KTR_{S}} \right)^{1/2}$$

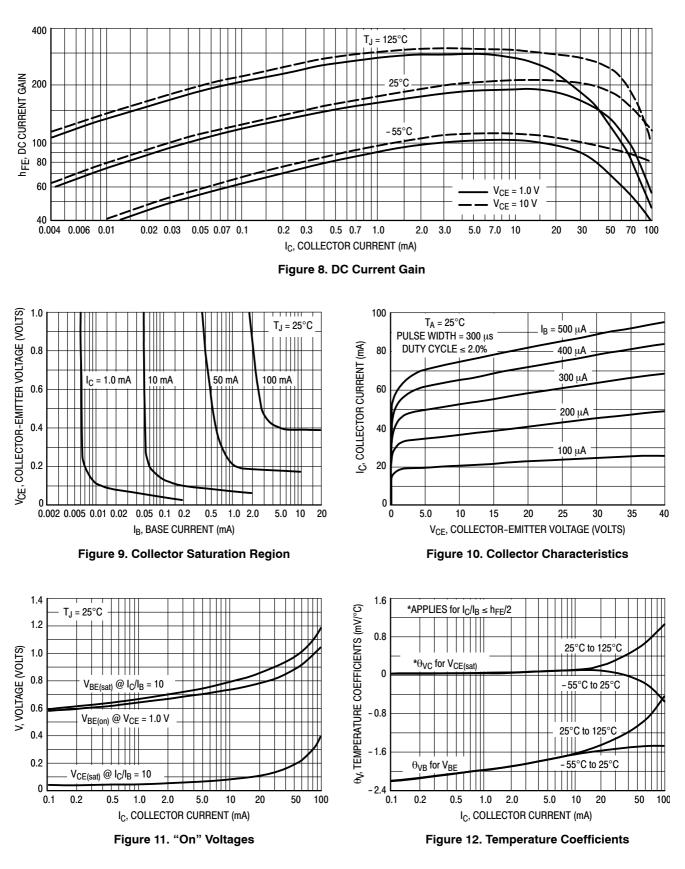
en = Noise Voltage of the Transistor referred to the input. (Figure 3)

 I_n = Noise Current of the Transistor referred to the input. (Figure 4)

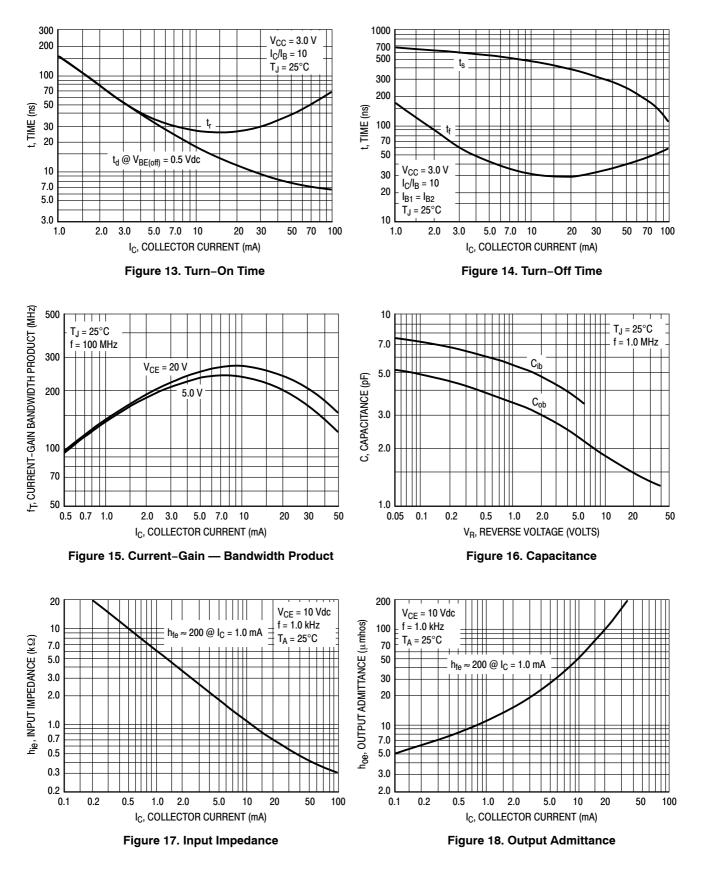
K = Boltzman's Constant (1.38 x 10⁻²³ j/°K)

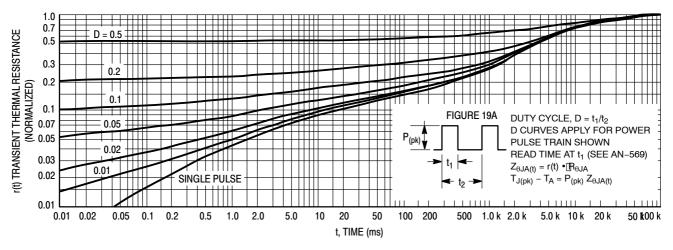
- T = Temperature of the Source Resistance (°K)
- R_S = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS

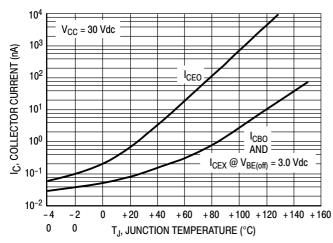


TYPICAL DYNAMIC CHARACTERISTICS











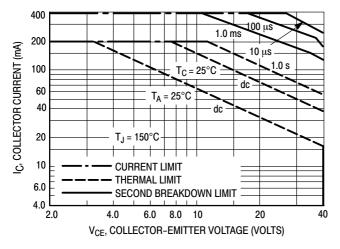


Figure 20.

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19A. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 19 was calculated for various duty cycles.

To find $Z_{\theta,JA(t)}$, multiply the value obtained from Figure 19 by the steady state value $R_{\theta,JA}$.

Example:

The MPS3904 is dissipating 2.0 watts peak under the following conditions:

 $t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms}. (D = 0.2)$

Using Figure 19 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

The peak rise in junction temperature is therefore

 $\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$

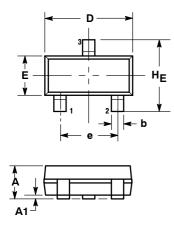
For more information, see AN-569.

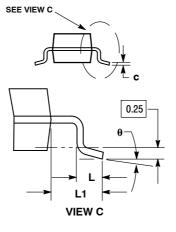
The safe operating area curves indicate I_C-V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 20 is based upon $T_{J(pk)} = 150^\circ\text{C}$; T_C or T_A is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 19. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





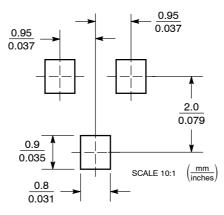
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
- THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	м	ILLIMETE	RS			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT



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